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NEWS RELEASE

Mitsui Kinzoku Increases Production Capacity of MicroThin™ for Package Substrates

- Increasing production capacity of Ageo Copper Foil Plant to 2 million m² per month -

Mitsui Mining & Smelting Co., Ltd. (President: Takeshi Nou; “Mitsui Kinzoku” hereinafter) is pleased to announce today that it has increased production capacity of extremely-thin electrodeposited copper foil with carrier for package substrate at Ageo plant (Ageo City, Saitama) by 0.5 million m² and achieved production volume of 2.0 million m² per month.

MicroThin™, extremely-thin electrodeposited copper foil with carrier is a product of Mitsui Kinzoku that has a copper foil of thickness 1.5 μm to 5 μm suitable for forming fine circuits and multiple types of fine-roughening treatment, and is mainly used for package substrate and motherboard for smartphones.

Demand for MicroThin™ for package substrate has been increasing along with full-scale spread of 5G, and we expect that demand continues to grow in the future.

MicroThin™ for package substrate has been supplied mainly from Ageo plant. However, Mitsui Kinzoku is currently transferring its manufacturing operations smoothly to a plant in Malaysia (Mitsui Copper Foil (Malaysia) SDN. BHD.).

On the other hand, for high-speed communication applications, Mitsui Kinzoku has started a mass production of MT-GN, which has finer circuit formation performance and superior properties required for high-speed high-frequency applications. (NEWS RELEASE dated on April 22, 2020) and has been increasingly adopted by customers.

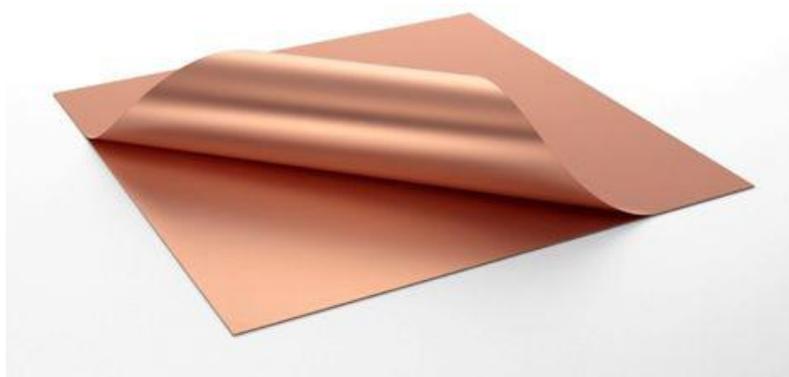
This production capacity enhancement at Ageo plant is intended to respond to growing demand for MT-GN and other high-end products of MicroThin™. Ageo plant has increased capacity from 1.5 million m² to 2.0 million m² per month by improving productivity through a realization of Smart Factories and technological innovation.

Under the slogan of *Taking full advantage of Material Intelligence*, we at Mitsui Kinzoku will continue to ensure stable product quality and sufficient supply capabilities for our customers while at the same time contributing to the creation of a sustainable society through our business activities.

Inquiries

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Picture of MicroThin™



Top: Copper carrier foil (thickness: 18 μ m or 12 μ m)

Bottom: Extremely-thin copper foil (thickness: 1.5 μ m to 5 μ m)

<For reference> Relationship to the Sustainable Development Goals (SDGs)

The SDGs are a set of 17 goals to be achieved by 2030. They were adopted by the UN at the UN General Assembly held in September 2015. This activity in the copper foil business apply to the SDGs below.

3: Good Health and Well-Being

9: Industry, Innovation and Infrastructure

We will continue to contribute to the achievement of the SDGs.